

## Statement on European Union End of Life Vehicle (EU ELV)

The EU ELV 2000/53/EC directive released on 18 September 2000 restricted the use of 4 heavy metals, Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+) and Cadmium (Cd) in vehicles. The amending document 2002/525/EC released 27 January 2003 provided maximum concentration values of 1000ppm for Pb, Hg, Cr6+ and 100ppm for Cd. TI semiconductor products declared by Texas Instruments (TI) to have an environmental rating of RoHS = "Yes" meet the ELV requirements without the need to claim any exemptions. TI products declared as RoHS = "Exempt" is also ELV Exempt. TI products that require an exemption for lead and lead compounds in components will claim one of the following ELV exemptions per Commission Delegated Directive (EU) 2020/363 of 17 December 2019, amending Annex II to Directive 2000/53/EC of the European Parliament and of the Council on end-of-life vehicles.

- 8(e) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
- 8(g)(i) Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages.  
Applies to vehicles type approved before 1 October 2022 and spare parts for these vehicles
- 8(g)(ii) Lead in solders to complete a viable electrical connection between the semiconductor die and the carrier within integrated circuit flip chip packages where that electrical connection consists of any of the following:
  - (i) a semiconductor technology node of 90 nm or larger;
  - (ii) a single die of 300 mm<sup>2</sup> or larger in any semiconductor technology node;
  - (iii) stacked die packages with dies of 300 mm<sup>2</sup> or larger, or silicon interposers of 300 mm<sup>2</sup> or larger.Applies to: Valid for vehicles type-approved from 1 October 2022 and spare parts for these vehicles
- 10(a) Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound.

Sincerely,



Randy Rath

TI SC Product Stewardship

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